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Full Material Declaration for attached parts list

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Diotec Semiconductor

Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 14 June 2016 [Approved on 20 November 2024, 07:45 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	3.89%	Silver	7440-22-4	19.44%
			Silicon	7440-21-3	80.56%
Die attach	Sn-Pb solder	4.37%	Silver	7440-22-4	2.73%
			Tin	7440-31-5	4.92%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.35%
Encapsulation	EP (Epoxy resin)	44.78%	Carbon black	1333-86-4	0.5%
			ALUMINUM(III) HYDROXIDE	21645-51-2	2.8%
			resin	9003-35-4	8.6%
			Epoxy resin 89	26335-32-0	18%
			Crystalline silica Exempt from other regulatory requirements	14808-60-7	70.1%
Leadfinish	Tin plating	0.55%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	46.41%	iron	14127-53-8	0.15%
			Copper	7440-50-8	99.85%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
TO-277 A / TO-277 B	Power SMD A/B	0.1	g